

Article

Novel Fabrication Tools for Dynamic Compression Targets with Engineered Voids Using Photolithography Methods

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Abstract:

Mesoscale imperfections, such as pores and voids, can strongly modify the properties and the mechanical response of materials under extreme conditions. Tracking the material response and microstructure evolution during void collapse is crucial for understanding its performance. In particular, imperfections in ablator materials, such as voids, can limit the efficiency of the fusion reaction and ultimately hinder ignition. To characterize how voids influence the response of materials during dynamic loading and seed hydrodynamic instabilities, we have developed a tailored fabrication procedure for designer targets with voids at specific locations. Our procedure uses SU-8 as a proxy for ablators materials and hollow silica microspheres as proxy for voids and pores. By using photolithography to design the targets' geometry, we demonstrate precise and highly reproducible placement of a single void within the sample, which is key for a detailed understanding of its behavior under shock compression. This fabrication technique will benefit high-repetition rate experiments at x-ray and laser facilities. Insight from shock compression experiments will provide benchmarks for the next generation of microphysics modelling.

Keywords: ICF; shock compression; void collapse; hydrodynamic simulations; hydrodynamic instabilities

I. INTRODUCTION

Mesoscale imperfections and inhomogeneities in structure and composition play a crucial role in the physical and chemical behavior of all materials. The mechanical properties and response of materials, especially at extreme conditions, e.g., at pressures above a Mbar, are largely dictated by microstructure and defect content. Material defects can be planar at domain interfaces or grain boundaries, linear like dislocations, or at a single point or location in a structure, such as chemical impurities or vacancies. An accumulation of defects or vacancies in any material can lead to void or pore space formation. The need to understand how voids and the void collapse process dictate materials performance under extreme conditions intersects many materials science applications and a range of disciplines, such as geophysics¹, planetary- and fusion energy sciences^{2,3}.

Characterization of the response of void defects and void collapse during dynamic compression is critical for predicting the microphysics dictating the material's response – as the collapse process can seed

hydrodynamic instabilities^{4–9}. One area of study where the material properties and the seeding of instabilities is particularly problematic is Inertial Confinement Fusion (ICF) physics¹⁰. Here, uniform spherical implosion of a fuel inside a capsule is necessary to generate thermonuclear ignition^{11,12}; potentially, ignition could open an exciting area of research for future global clean energy solutions, termed Inertial Fusion Energy (IFE)^{13–16}. However, the presence of defects, particularly voids, in the ablator layer, *i.e.*, outermost material of the capsule, has been recognized as one of the major contributions to performance degradation due to instability seeding and growth¹⁷. Micron-sized voids and pores in the ablator layer have been suggested to possibly cause jetting as the collapse process generates ejecta with roughly double the particle velocity of the bulk material, launching Rayleigh-Taylor hydrodynamic instabilities^{18–20}, which limits compression of the fuel and fusion performance. A precise understanding of the response of mesoscale defects, such as voids, in the ablator material, is thus key for advancing ICF and IFE.

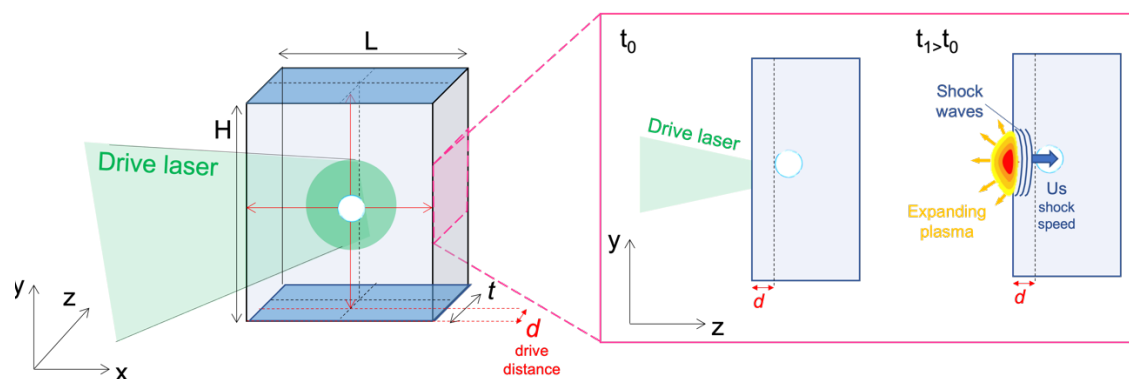


Figure 1. Left: schematic view of ideal sample for void collapse; the compression is driven by a high-power laser focused on the sample's drive surface (x - y plane). The inset on the right shows the working principle of laser-driven shock-compression: the formation of an expanding plasma at the drive surface generates shock waves that compress the sample along the laser propagation direction (z).

New experimental benchmark data are required to refine current microphysics models of void collapse under shock compression, which include a combination of material strength, radiation transport, instability tracking, equation of state and transport properties²¹. To specifically tackle understanding of how voids dictate a material's response to dynamic compression, a well-characterized void feature is needed. To do this, we created a fabrication procedure to enable design and characterization of a simplified system, *i.e.*, an isolated void and its interaction with the propagating shock wave and the surrounding material. Dynamic compression is achieved by focusing a high-power laser onto the sample to generate ablation-driven shock compression (Figure 1, right panel). As shown in Figure 1, a specific placement of the void within the sample is required by the experimental geometry. To ensure homogeneous spatial compression, the void needs to be centered with respect to the drive surface, *i.e.*, the xy -plane in Figure 1. Furthermore, the distance between the void and the drive surface (d along the z -axis in Figure 1) should be tunable.

Here, we present photolithography-based fabrication of targets for dynamic compression containing isolated voids. This method allows for large-scale production of designer targets with tuned microstructures and properties, a key feature for the future of x-ray free electron laser (XFEL) studies of mesoscale features. Indeed, with the expected upgrades of optical driver lasers to 1Hz frequency, high-repetition rate laser experiments will require large-scale target production²² (*i.e.*, one sample and one compression every second, compared to the current shot cycle of 5-7 minutes). Precise and reproducible placement of an isolated void within the sample is viable with this methodology; the study of such simplified systems will provide precise and detailed insight into the behavior of micron-sized voids under dynamic compression. This fabrication method can also be extended to other fields of high-energy density science, *e.g.*, viscosity measurements that use isolated heterogeneities embedded in the bulk^{23–25}. Large-scale, designer target fabrication procedures will also be

key in the development of the IFE industry, where 10 Hz rep-rated laser technology could drive the foundational design of future fusion power plants²⁶.

II. METHOD

II.A Materials

Polystyrene (C_8H_8)_n and other plastic materials, e.g. glow deposition polymer^{27–30}, are commonly used as ablator materials in ICF experiments. Here, to investigate their properties and the interaction of defects with a propagating shock wave, we have used the photoresist SU-8³¹ as a proxy. SU-8, made by Kayaku Advanced Materials, is a mixture of photosensitive epoxy resin, epoxy novolac polymer, and various solvents. The mixture is a viscous liquid that can be easily deposited and spun into layers. The solvents and their proportions can be manipulated to achieve different viscosities, which can produce layers with thicknesses ranging from 0.5 μm to >200 μm . The SU-8 epoxy cross-links and hardens when exposed to ultraviolet light (optimal wavelength 365 nm), and the unexposed parts can be dissolved³². By using appropriate photolithography masks, this allows the production of geometries with high precision.

The experimental requirements for these targets are multifaceted – not only they need to be similar in properties and shock response to traditional polymer ICF ablaters, but they also need to have uniform thickness for dynamic X-ray imaging measurements and be uniform laterally for steady shock propagation. SU-8 has similar density (1.2 g/cm³)³³, mechanical (Young's modulus 4.1 GPa)³⁴ and optical (refractive index 1.6)³⁵ properties as polystyrene³⁶. The practical advantages when using SU-8 as a proxy for other polymers is that being a photoresist it can be spun over a substrate to obtain a homogeneous layer. Moreover, photolithography enables production of devices with specific geometries and a resolution on the order of few micrometers. The final result is an optically transparent device whose thickness can be specified by spinning various formulations of SU-8 of the appropriate viscosity (commercially available) and tuning the spinning speed and duration. In particular, for our study the quality of the lateral walls is crucial, and SU-8 enables control and fabrication of nearly vertical sidewalls, even in devices with very high aspect ratios^{37–39}: this will ensure the planarity of the driven shock as well as the ability to use a suite of characterizations, e.g., velocimetry for pressure measurements⁴⁰ or X-ray based imaging techniques^{41–45}.

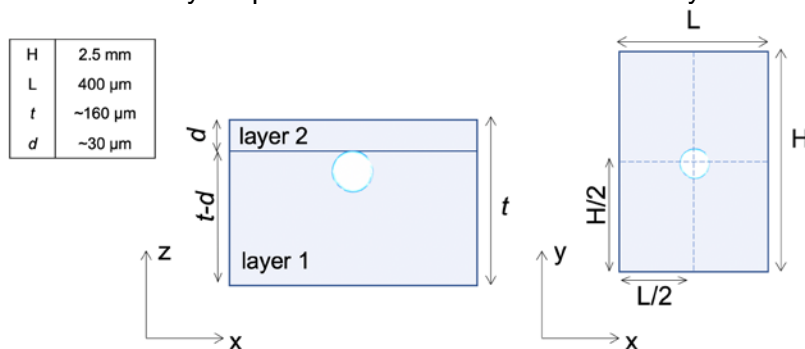


Figure 2. Schematic view of ideal sample geometry for X-ray imaging experiment under shock compression.

In our fabrication procedure, we used hollow silica glass shells as a proxy for the actual voids. Such hollow glass shells are commercially available (Cospheric) as microspheres made of a proprietary soda-lime borosilicate formulation, with nominal wall thicknesses up to a few μm . Hollow microspheres with metallic coatings are also available, which can be used to tune their mechanical as well as conductive properties. There are numerous advantages in using silica microspheres over other void-fabrication techniques like laser milling: (i) versatility, as the microspheres are available in a wide range of sizes 5–125 μm ; (ii) cost reduction, as the microspheres can be purchased in large quantities and are relatively inexpensive; (iii) time-saving, as for each SU-8 spinning numerous void-bearing devices can be produced, as opposed to the time required to prepare the bare devices and individually laser-mill the desired void for each device. Furthermore, the ability to produce many samples with a single spinning procedure also ensures high homogeneity within each batch. The effectiveness and scalability of this fabrication approach procedure make it suitable for the next

generation of ICF and high-energy density XFEL-based experiments, as it can meet the increased need for targets once high repetition rate driver lasers are available.

II.B Experimental procedure

The ideal target design for ICF void-bearing ablaters is shown in Figure 2. As previously mentioned, the void should be centered in the laser drive surface (xy-plane) and placed at a specific distance d from the drive surface (i.e., along the z-axis). Specifically, for our experiments we used $\sim 40\ \mu\text{m}$ hollow silica microspheres (HSG 38-45ect) and the desired d value was $\sim 30\ \mu\text{m}$. However, the size of the microsphere as well as the device's dimensions can easily be tuned using this fabrication procedure. We developed our fabrication procedure at the Stanford Nano Shared Facilities (SNSF) at Stanford University, CA (USA). SU-8 was spun onto a substrate using a Headway PWM32-PS-CB15 spinner; several layers can be superposed before exposure, allowing to build up stratified devices of the desired thickness t . For our experiments, we have used a 3" silicon wafer as substrate, and spun over different metal layers (i.e., 50 nm of copper adhesion layer and titanium coating) to increase the adhesion and thickness uniformity of the photoresist during spinning. The microspheres were heated at 150°C for about 15-20 minutes to dry out adsorbed moisture on the surfaces and separate beads that were clumped together, allowing them to fall individually.

From preliminary tests with the $40\ \mu\text{m}$ microspheres, we have noticed full wetting of the beads after dispersion onto an unexposed SU-8 layer, so we designed the target fabrication as follows. For a device of desired thickness t and bead-drive distance d (see Figure 1-2): (i) spin a layer of SU-8 of thickness $t-d$; (ii) deposit the bead, by either sprinkling them or by singularly place them onto the substrate; (iii) spin an additional layer of SU-8 of thickness d . In this way, the microspheres are fully wetted by the layer 1 and sink to the level, so d can be directly tuned by changing the spinning parameters of layer 2. The parameters from our optimized fabrication procedure are reported in Table 1.

Layer	Thickness	Value [μm]	Spin speed [RPM]	Ramp [RPM/s]	Time [s]	Bake temp. [°C]	Bake time [min]
Layer 1	t - d	130	500	100	10	65;	7;
			1500	300	30	95	40
Deposit hollow microspheres							
Layer 2	d	30	500	100	10	95	5
			3300	300	30		

Table 1. explanation of parameters

Within the SNSF, a Durham Magneto Optics ML3 MicroWriter direct write (maskless) exposure machine operating at 385 nm was available. Despite 385nm not being the optimal wavelength to cross-link SU-8, the photoresist could still be successfully processed by increasing the exposure dose to achieve full cross-link (Figure 3). Further experimentation with dose and defocus helped to enhance the sidewall geometry to make optically smooth, near vertical sidewalls. With respect to our procedure, the exposure dose and processing time can be reduced by using the most suited 365 nm UV wavelength. Prior to doing any exposures, we used the microscope of the direct write machine to examine the substrate and the SU-8; the beads are clearly visible showing a bright reflection from their exact center; once aligned carefully to the cross-hairs, their precise coordinate positions in X and Y can be noted with ~ 1 -micron accuracy; a rectangular mask pattern of the desired dimensions (in our case $400\ \mu\text{m} \times 2.5\ \text{mm}$) was designed centered in X and Y. Setting up the machine to expose the rectangular patterns sequentially on the precise coordinates for each pattern ensures a precise placement of the bead in the xy-plane for each device (Figure 1); furthermore, this approach can be readily expanded to different target and/or bead placement geometries simply modifying the exposure mask design. For our optimized fabrication procedure, we used a 10X microscope, and lens setting with nominal exposure resolution of $1\ \mu\text{m}$; we estimate our actual resolution to be of the order of $2\text{-}3\ \mu\text{m}$, as we slightly overexposed our devices to ensure complete cross-link of the epoxy and good mechanical properties

under shock-compression (3000 mJ/cm^2 , see Figure 3). Slight over-exposure was preferred for this protocol to compensate eventual shadowing from the microsphere, as shown in Figure 6 and discussed in the following section.

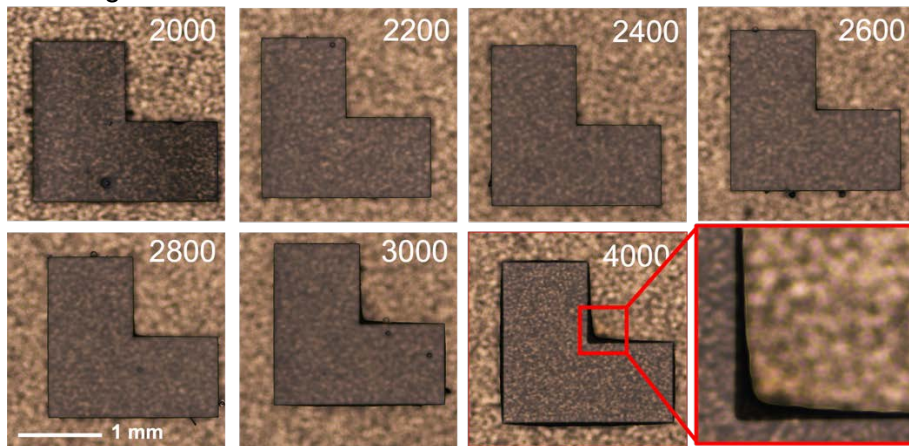


Figure 3. Example of exposure tests, in which the exposure dose was systematically changed; the numbers on each figure indicate the exposure dose for each device (expressed in mJ/cm^2).

After exposure, the spun SU-8 was baked at 65° for 5 minutes and then at 95° for 13 minutes. Subsequently, the whole wafer was submerged in SU-8 Developer (mfg. by Kayaku Materials) for 15 minutes and gently turned to dissolve all the non-exposed photoresist. After this step, only the exposed cross-linked region, *i.e.*, the devices, remain on the substrate while the rest of the SU-8 is dissolved and rinsed away. After development and full cross-link, the SU-8 adhesion to the substrate decreases, and the devices can be mechanically detached from the substrate using a fine and anti-scratch tweezer for leverage. We have tested other extraction methods, such as dissolving a sacrificial layer of Al or Cu, but we have discovered that the metal etchants unexpectedly dissolve the SU-8 and/or compromise the optical quality of the devices' walls. However, the possibility of mechanically extract the devices simplifies the procedure, as it doesn't require rinsing, filtering and recovering of the parts from the etchants.

Furthermore, we noted the use of a metallic layer on top of the Si substrate facilitates mechanical extraction of the devices, which can be easily peeled off the wafer without damages. The final step for completing curing and hardening of the extracted targets was a 10-minute bake at 150°C .

III. RESULTS

Following the procedure detailed in Section II, up to 50-60 void-bearing SU-8 devices can be fabricated from a single SU-8 processing, ensuring high homogeneity within each batch. After completing the fabrication, we used X-ray computed tomography (CT) to determine whether the procedure had affected the voids; the results are shown in Figure 4. X-ray CT is a non-destructive scanning X-ray imaging technique that, by collecting angle-resolved X-ray images of the sample, can provide reconstructed 2D slices at specific depths within the sample⁴⁶. Figure 4(a) shows the reconstructed slice at the center of the device; the microsphere size ($\sim 40 \mu\text{m}$ diameter) and the void depth d ($\sim 30 \mu\text{m}$) are consistent with the expected values. Importantly, X-ray absorption was measured along the yellow line in Figure 4(a). The results are reported in Figure 4(b) and show that the region inside the void display the same X-ray absorption as the air surrounding the device, which implies that no chemical or solvent penetrates the glass walls, and the microspheres remain empty throughout the whole fabrication procedure. Thus, the hollow silica microspheres embedded in cross-linked SU-8 following our experimental protocol are suited proxy for actual voids within the sample.

We performed further imaging characterization to confirm the microsphere placement within the device, as well as checking the optical quality of the devices' lateral walls; the results are reported in Figure 5. The optical image in Figure

5 (c,d) shows the “top view”, which corresponds to the xy -plane in Figures 1-2, *i.e.*, the surface on which the driver laser is focused for laser-driven shock-compression. As previously mentioned, shock-compression experiments require the voids to be centered in this surface to ensure planar and homogeneous compression. Precise placement of the microsphere was successful using photolithography to cross-link the SU-8 in a region centered around an isolated microsphere (Sect. II-B). We have also analyzed the placement of the void along the direction of the shock propagation, *i.e.*, the z -axis in Figures 1-2. The optical image reported in Figure 4(a) shows that our results are consistent with the desired value of $\sim 30\ \mu\text{m}$, thus the fabrication procedure allows us to accurately define this distance by optimizing the spinning conditions of the second SU-8 layer (Sect. II-B). However, optical measurements through a transparent medium could be affected by aberrations, especially when looking at the “side view”, as the images are collected through a $400\ \mu\text{m}$ -thick layer of SU-8. For this reason, we have also used X-ray imaging techniques (X-ray CT in Figure 4 and XFEL-based X-ray imaging in Figure 5(b)) to confirm the value and the reproducibility of the desired void-drive distance d . Our fabrication procedure is thus suited for the design of devices embedding voids at specific locations, as shown in Figure 5, and the results were highly reproducible over hundreds of devices. It is also worth noting that our ability to obtain clear images of the beads through $100\ \mu\text{m}$ up to $400\ \mu\text{m}$ of SU-8 demonstrates the high optical quality of the devices’ lateral walls.

As detailed in Sect. II-B, we have spun the thick layer incorporating the voids first, and then a second layer to ensure that the microspheres are at the desired depth d within the sample. Besides the advantage of an easily tunable procedure to optimize d , this choice was also dictated by the necessity to ensure full exposure through the total thickness of the device. Indeed, the microspheres dispersed in the SU-8 can cause shadowing during the photolithography process and affect full cross-link of the region beneath them; results from our preliminary tests are reported in Figure 6. As visible by the “side view” of these devices, having the microsphere on top of a thick layer (Figure 6(a)) can mitigate the shadowing effects experienced by a microsphere placed closer to the wafer substrate (Figure 6(b)). It is probable, indeed, that having more space between the silica shell and the metallic substrate allows for more photons to be reflected from the metallic surface of the substrate. Thus, even if not by direct irradiation, the region beneath the microsphere is still exposed, and it cross-links. On the contrary, when the microsphere is too close to the bottom of the device, the shadowing effects dominate, and the region beneath it is not exposed such that the sphere sinks to the bottom, as shown in Figure 6(b). This further emphasizes the importance of the slight overexposure of the device that we adopted. Indeed, not only it ensures cross-link of bare SU-8, but also full exposure beneath the microsphere, in the region shadowed from direct irradiation.

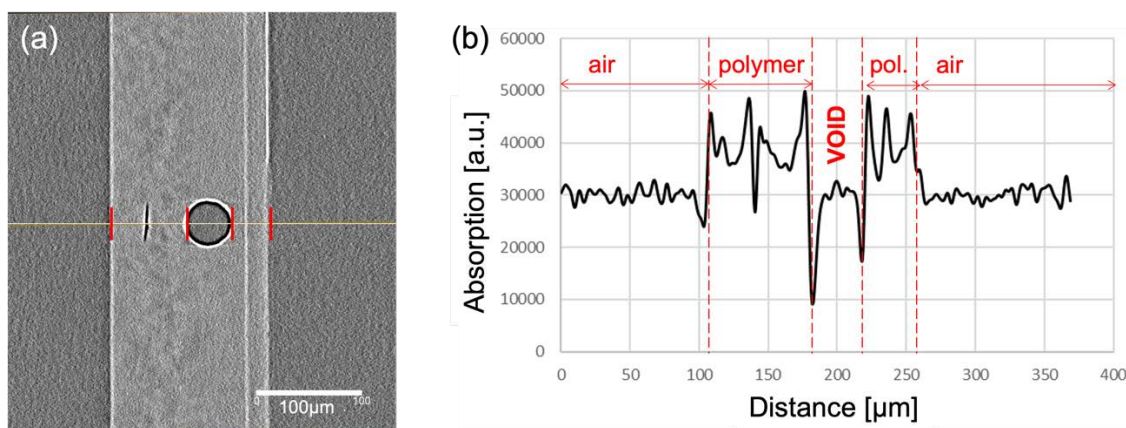


Figure 4. X-ray CT measurements of a representative eSU-8 void-bearing target (Carl Zeiss X-ray Microscopy Inc. Xradia Versa 520). (a) 2D reconstructed slice at the void center. (b) X-ray absorption as measured along the yellow line in (a); the different parts and materials are indicated.

SIDE VIEW

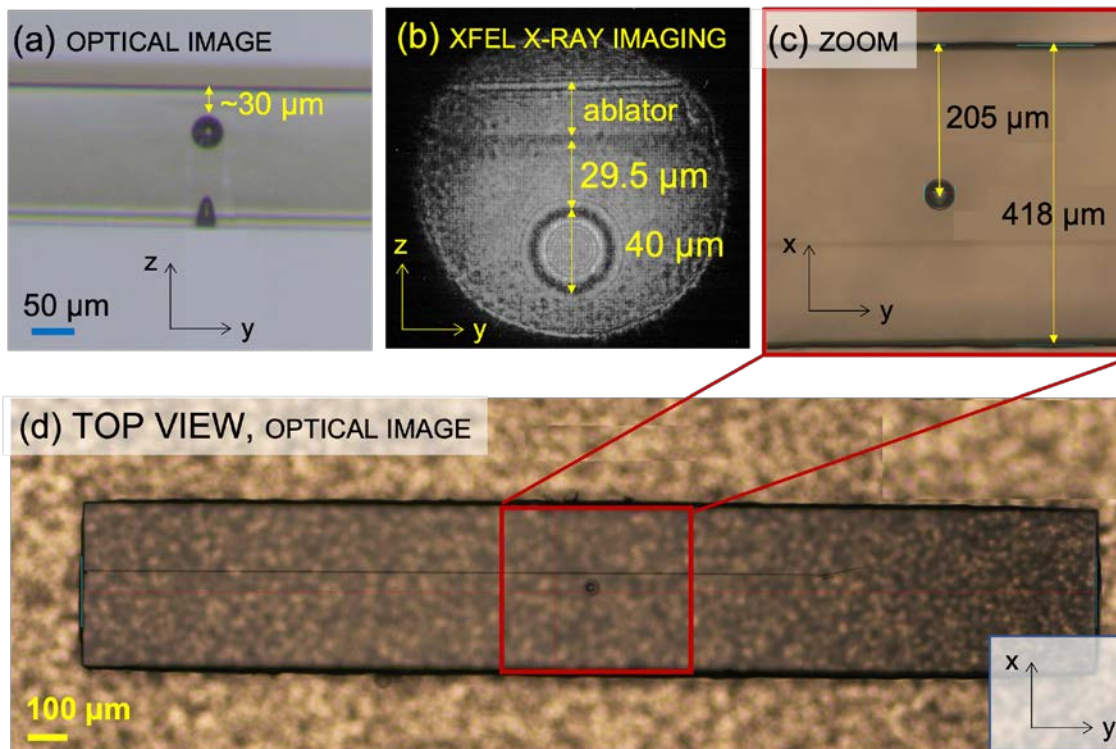


Figure 5. Representative images of void-bearing SU-8 targets; both optical (a,c,d) and x-ray (b) images confirm the production of targets with the desired geometry.

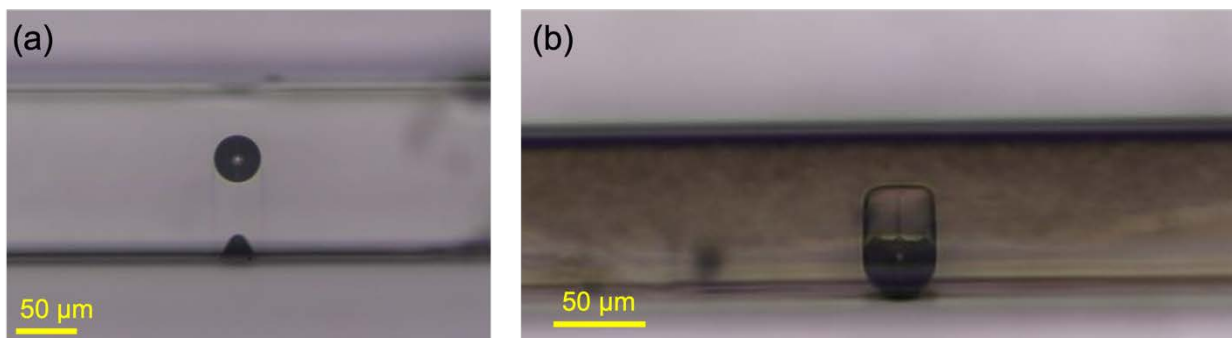


Figure 6. Optical microscopy images showing the effects of shadowing from the microsphere over the SU-8 cross-link. (a) shadowing is mitigated by spinning the thicker layer first; (b) when the microsphere is closer to the substrate, the region beneath it is not cross-linked and the sphere sinks to the bottom.

IV. SUMMARY

We have developed and tested a fabrication procedure that allows for large-scale production of void-bearing targets for dynamic compression experiments. We used SU-8 photoresist and hollow silica microspheres as proxies for void-bearing ICF ablator materials. Our fabrication procedure exploits spinning of SU-8 layers at the designated thicknesses and the use of specifically designed photolithography masks to ensure placement of the void at a desired location within the target. Imaging and absorption data confirm the viability of this approach and the reproducibility of the results over hundreds of targets. Furthermore, production of up to 50-60 targets can be achieved within a single fabrication procedure, ensuring high uniformity over several tens of devices. Scalability and high reproducibility make this technique suited for future studies at high repetition

rate, and the fabrication details can be also optimized for different experimental scopes, e.g., using metal-coated or filled spheres for viscosity measurements.

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